

# TG-PP-10

## Silicone Thermal Putty

### Description

TG-PP-10 is a one-part thermal conductive interface material based on silicone resins. It does not bleed and flow. It is designed for very good thermal conduction with high electrical insulation.

### Applications

Thermal conductive interface material for electronic parts and devices.

### Guidelines for use

1. Thaw the silicone to room temperature before use
2. Wear rubber glove when handling the silicone putty
3. Scoop a quantity of the silicone putty from the container using a stainless steel spoon
4. Work and knead the putty around electronic part and circuit by hand
5. Wipe off any excess party with a piece of dry cloth. Further cleaning of residues may be achieved by wiping with cloth wetted with isopropanol

### Properties

Property	Typical Value	Unit	Test Method
Chemical type	Silicone	-	-
Appearance	White Putty	-	Visual
Mix ratio, by weight	1 component	-	-
Shelf life	6	Month	-
Viscosity, Brookfield RVT, 25°C	Putty	cP	ASTM D792
Specific gravity, 25°C	3.2	-	ASTM D792
Thermal Conductivity	10	W / mK	ISO/DIS 22007
Hardness	50	Shore 00	ASTM D2240
Storage Temperature	-50 to 200	°C	-

### Storage

Tightly close original container of unused product and store in dark and cool place

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